



Designation: ~~F68-05~~^{ε1} Designation: **F68 - 10**

Standard Specification for Oxygen-Free Copper in Wrought Forms for Electron Devices¹

This standard is issued under the fixed designation F68; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

~~ε¹Note—Section 2 was corrected editorially in August 2009.~~

1. Scope*

1.1 This specification establishes the requirements for wrought and fabricated shapes made from Copper UNS² No. C10100, conforming to the chemical requirements of Specification B170, Grade 1, and suitable for use in electron devices.

1.2 The requirements of this specification are in addition to those prescribed in the following product specifications appropriate to the material being ordered: B1, B2, ~~B3~~, B75, B75M, B152/B152M, B170, B187/B187M, ~~B188~~, B272, and B372. In case of conflict, however, this specification shall take precedence.

~~1.3 The inch-pound units are the standard for this specification except for grain sizes which are in metric units. Metric values given in parentheses are for information only.~~

1.3 The values stated in inch-pound units are to be regarded as standard. The values given in parentheses are mathematical conversions to SI units that are provided for information only and are not considered standard.

1.3.1 Exception—grain sizes are in metric units and are standard.

1.4 The following safety hazard caveat applies to sections 17.4, 17.5 and 18.7 of this specification: *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.*

2. Referenced Documents

2.1 *ASTM Standards:*³

B1 Specification for Hard-Drawn Copper Wire

B2 Specification for Medium-Hard-Drawn Copper Wire

B3 Specification for Soft or Annealed Copper Wire

B75 Specification for Seamless Copper Tube

B75M Specification for Seamless Copper Tube (Metric)

B152/B152M Specification for Copper Sheet, Strip, Plate, and Rolled Bar

B170 Specification for Oxygen-Free Electrolytic Copper Refinery Shapes

B187/B187M Specification for Copper, Bus Bar, Rod, and Shapes and General Purpose Rod, Bar, and Shapes

B188 Specification for Seamless Copper Bus Pipe and Tube

B193 Test Method for Resistivity of Electrical Conductor Materials ~~B248 Specification for General Requirements for Wrought Copper and Copper-Alloy Plate, Sheet, Strip, and Rolled Bar~~

~~B248M Specification for General Requirements for Wrought Copper and Copper-Alloy Plate, Sheet, Strip, and Rolled Bar (Metric)~~

~~B249/B249M Specification for General Requirements for Wrought Copper and Copper-Alloy Rod, Bar, Shapes and Forgings~~

~~B250/B250M Specification for General Requirements for Wrought Copper Alloy Wire~~

B272 Specification for Copper Flat Products with Finished (Rolled or Drawn) Edges (Flat Wire and Strip)

¹ This specification is under the jurisdiction of ASTM Committee B05 on Copper and Copper Alloys and is the direct responsibility of Subcommittee B05.02 on Rod, Bar, Wire, Shapes and Forgings.

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² The UNS System for copper and copper alloys (see Practice E527) is a simple expansion of the former standard designation system accomplished by the addition of a prefix "C" and a suffix "00". The suffix can be used to accommodate composition variations of the base alloy.

³ For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

*A Summary of Changes section appears at the end of this standard.

- B372 [Specification for Seamless Copper and Copper-Alloy Rectangular Waveguide Tube](#)
- B577 [Test Methods for Detection of Cuprous Oxide \(Hydrogen Embrittlement Susceptibility\) in Copper](#)
- B846 [Terminology for Copper and Copper Alloys](#)
- E29 [Practice for Using Significant Digits in Test Data to Determine Conformance with Specifications](#)
- E112 [Test Methods for Determining Average Grain Size](#)
- E527 [Practice for Numbering Metals and Alloys in the Unified Numbering System \(UNS\)](#)

2.2 *ASTM Adjunct:*
Comparison Chart⁴

3. Terminology

3.1 For definitions of terms related to this product, refer to the terminology sections of Specifications B3, B188, B248, B248M, B249/B249M, B250/B250M, or B251. For definitions of terms related to this product, refer to Terminology B846.

3.2 *Definition of Terms Specific to This Standard:*

3.2.1 *extrusion pipe, n*—a lamination resulting from the flow of the oxide surface of a billet into the article being extruded and usually confined to the trailing-end portion of the extruded product. ~~3.2.2 *oxygen-free, adj*—electrolytic copper produced substantially free of cuprous oxide and containing no more than 10 ppm oxygen, as determined by metallographic examination at 75× under polarized light, and manufactured without the use of metallic or metalloidal deoxidizers.~~

~~3.2.3 *oxygen-free, grade 1, adj*—as defined in 3.2.2 except that the oxygen content must be 5 ppm maximum. This copper is also commonly termed “oxygen-free electronic.”~~

~~3.2.4~~

3.2.2 *rms, n*—root-mean-square, a statistical measure of surface roughness usually determined by means of a profilometer.

4. Ordering Information

4.1 Orders for the product shall include the following information:

- 4.1.1 The designation and year of issue of both Specification F68 and the basic product specification involved,
- 4.1.2 Shape of product,
- 4.1.3 Size,
- 4.1.4 Total estimated weight or number of pieces, or both, for each size and shape,
- 4.1.5 The Specification F68 Class of material,
- 4.1.6 Intended application (for example, wave guide),
- 4.1.7 Temper,
- 4.1.8 Heat identification or traceability details,
- 4.1.9 Certification,

4.2 The following options are available:

- 4.2.1 Mill test report,
- 4.2.2 Special packaging,
- ~~4.2.3 Special marking,~~
- 4.2.3 Special marking,
- 4.2.4 If special temper requirements for sheet and strip for gasket applications are required.

5. Materials and Manufacture

5.1 *Material*—The material shall be oxygen-free electronic copper which conforms to the requirements of Specification B170, Grade 1.

5.2 *Manufacture*—The manufacturing process shall conform to the requirements of this specification and to the basic product specification to which the product was ordered.

6. Chemical Composition

6.1 The cast refinery shape shall conform to the requirements specified in Specification B170, Grade 1, Table 1.

6.1.1 Copper shall be taken as the difference between the sum of results for Grade 1 specified elements in Table 1 and 100 %.

6.2 These composition limits do not preclude the possible presence of other unnamed elements. Limits may be established and analysis required for ~~unnamed~~ unnamed elements not specified in Table 1 of B170 by agreement between the manufacturer and the purchaser.

7. Temper

7.1 The temper of the wrought or fabricated product supplied shall conform to the requirements of the basic product specification to which it was ordered.

⁴ Available from ASTM International Headquarters. Order Adjunct No. ADJF0068. Original adjunct produced in 1966 .

8. Physical Properties

8.1 *Electrical Resistivity*—The maximum mass resistivity shall be 0.15176 ohms g/m² (conductivity 101.0 % minimum, International Annealed Copper Standard (IACS) at 20°C when tested in the annealed condition.

8.2 *Scaling*—When agreed upon between customer and supplier, the test specimens of oxygen-free copper shall show substantial surface oxide adherence when subjected to test as described in 18.7.

NOTE 1—The purpose of this test is to distinguish between oxygen-free copper and deoxidized copper. Deoxidized copper will not retain the surface oxide in this test.

9. Mechanical Properties

9.1 All products shall conform to the mechanical property requirements of the basic product specification to which the item was ordered, with the following exception:

9.1.1 Sheet and strip with a thickness of 0.125 in. or less and intended for gaskets or for deep drawing shall conform to the requirements prescribed in Table 1-, and when so specified 4.2.4 of Ordering Information.

10. Hydrogen Embrittlement (Reverse Bend Test Method)

~~10.1 Specimens shall withstand a minimum of ten reverse bends without breaking. Evidence of blisters, upon visual examination, shall be cause for rejection.~~

10.1 Specimens shall withstand a minimum of ten reverse bends without breaking when prepared in accordance with B577 Test Method D. Evidence of blisters, upon visual examination, shall be cause for rejection.

NOTE 2—Fractured areas of the bent samples should show some reduction in area and have a distorted, smeared surface. The ideal break will have the appearance of a cup and cone tensile failure.

11. General Examination

11.1 When examined the samples shall have:

11.1.1 A relatively uniform surface free of irregular rough spots sometimes termed open grains,

11.1.2 Edges free of seams, laps and cracks,

11.1.3 Cross sections free of breaks, inclusions or extrusion pipe.

12. Special Examinations

12.1 *Special Macro Examination:*

12.1.1 The samples shall show no subsurface defects in excess of the following limits:

12.1.1.1 *Tubular Products:*

(1) *Tubes for Exhaust (Pinch-off) Purposes:*

(a) For wall thickness over 0.1 in. (2.5 mm), no defects on the external surface deeper than 0.005 in. (0.13 mm).

(b) For wall thicknesses up to 0.1 (2.5 mm) inclusive, no defects on the external surface deeper than 5 % of the wall thickness.

(c) No significant defects on the inside surface when examined with fiber optics or a boroscope.

(2) *Waveguides*—No defects on the external surface deeper than 0.005 in. (0.13 mm) or 5 % of the wall thickness, whichever is smaller. No significant defects on the inside surface when examined with fiber optics or a boroscope.

(3) *Tube for Other Applications*—No defects on either the internal or external surfaces deeper than 0.020 in. (0.51 mm) or 5 % of the wall thickness, whichever is the smaller.

12.1.1.2 *Bar and Plate Products*—No defects deeper than 0.06 in. (1.6 mm) or 5 % of the thickness, whichever is the smaller.

12.1.1.3 *Sheet, Strip and Flat Wire Products*—No defects deeper than 0.005 in. (0.13 mm) or 5 % of the thickness, whichever is smaller.

12.1.1.4 *Rod and Wire Products:*

(1) *Rod and Wire less than 0.19 in. (4.8 mm) in Diameter*—No defects deeper than 0.005 in. (0.13 mm) or 5 % of the diameter, whichever is smaller.

(2) *Rod and Wire 0.19 in. (4.8 mm) and Over in Diameter*—No defects deeper than 0.06 in. (1.6 mm) or 5 % of the diameter, whichever is smaller.

12.2 *Special Microscopical Examination:*

12.2.1 Samples shall be classified by comparison to Plate 1, which is available from ASTM International Headquarters as an adjunct (see 2.2).

TABLE 1 Grain Size

Thickness	Average Grain Size, max, mm	Hardness HRF ^A max
Less than 0.040 in. (1.0 mm)	0.035	75
0.040 to 0.125 in. (1.0 to 3.2 mm)	0.050	75

^A For information only.